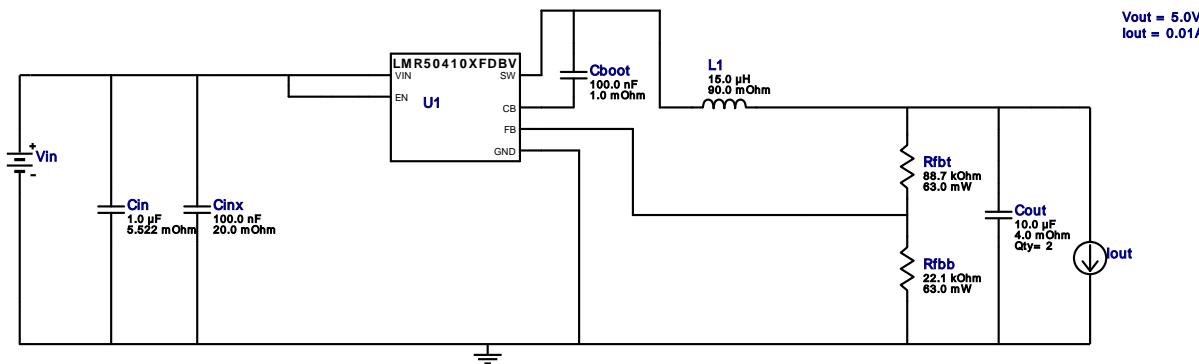


# WEBENCH® Design Report

Design : 7839 LMR50410XFDBVR  
LMR50410XFDBVR 6V-36V to 5.00V @ 1A

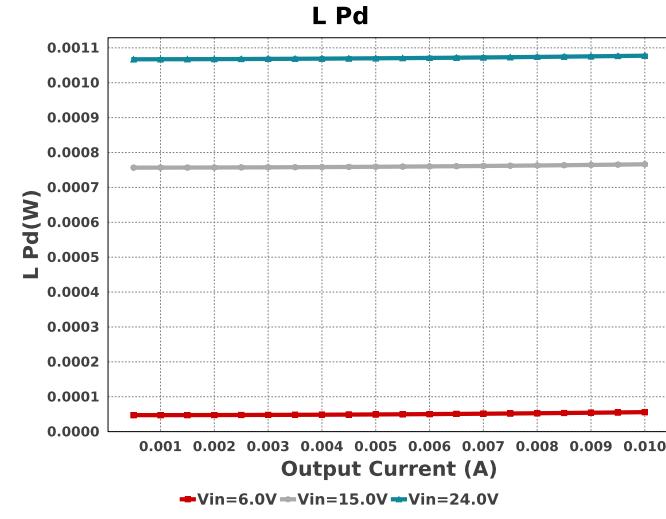
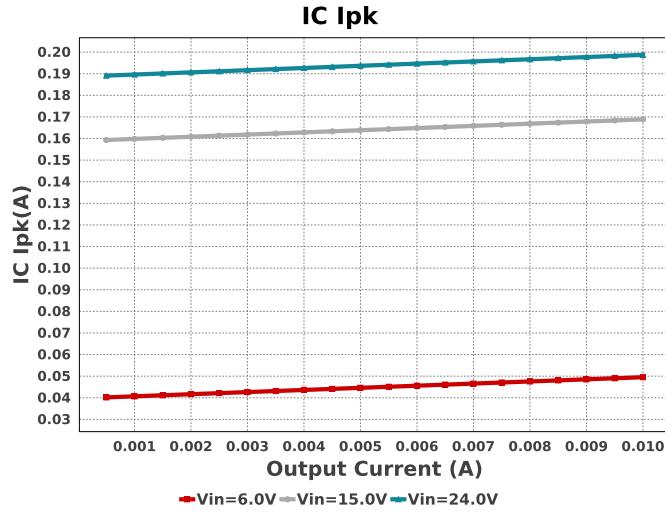
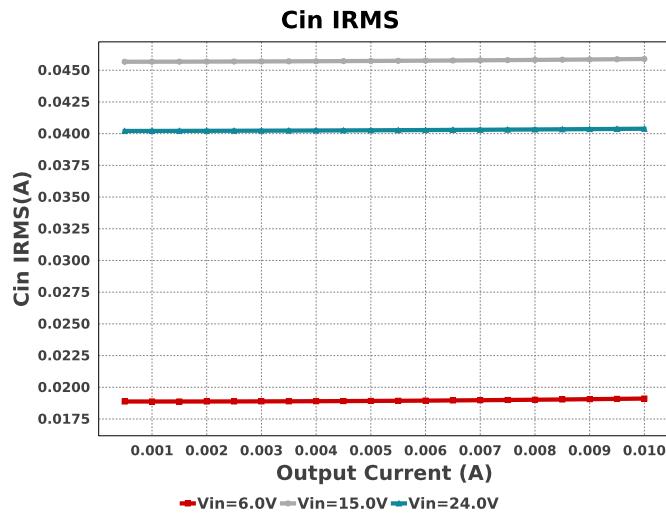
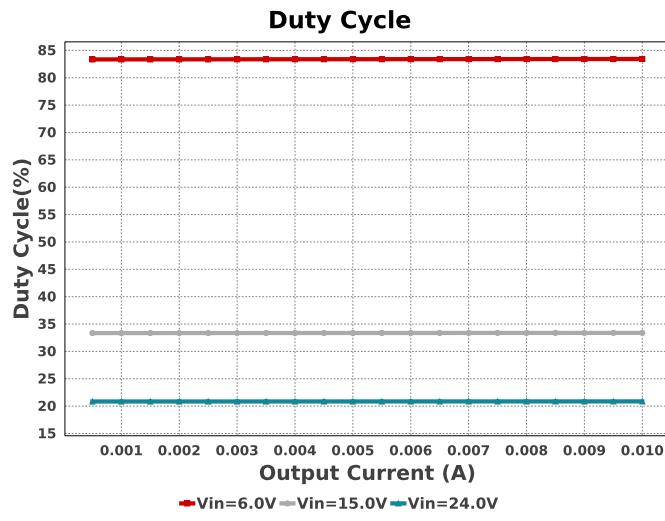
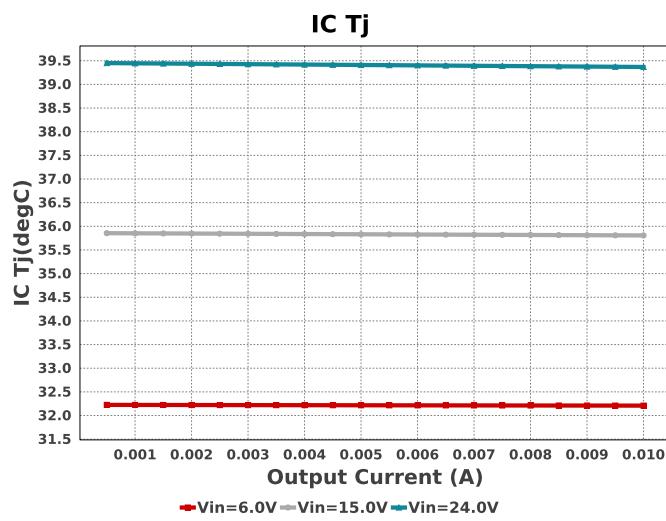
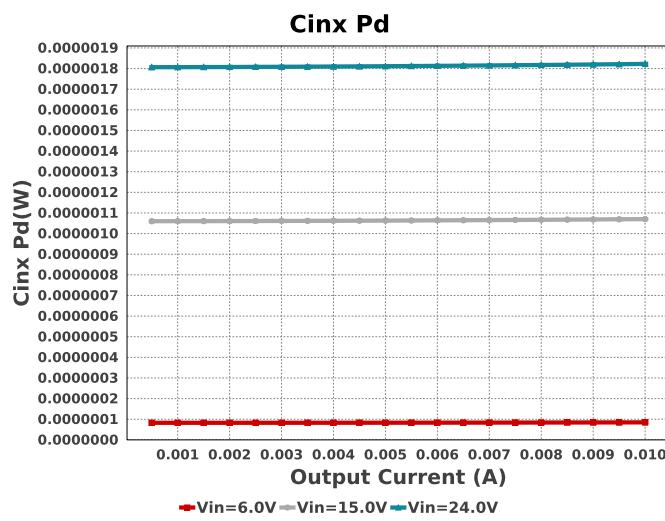
VinMin = 6.0V  
VinMax = 24.0V  
Vout = 5.0V  
Iout = 0.01A

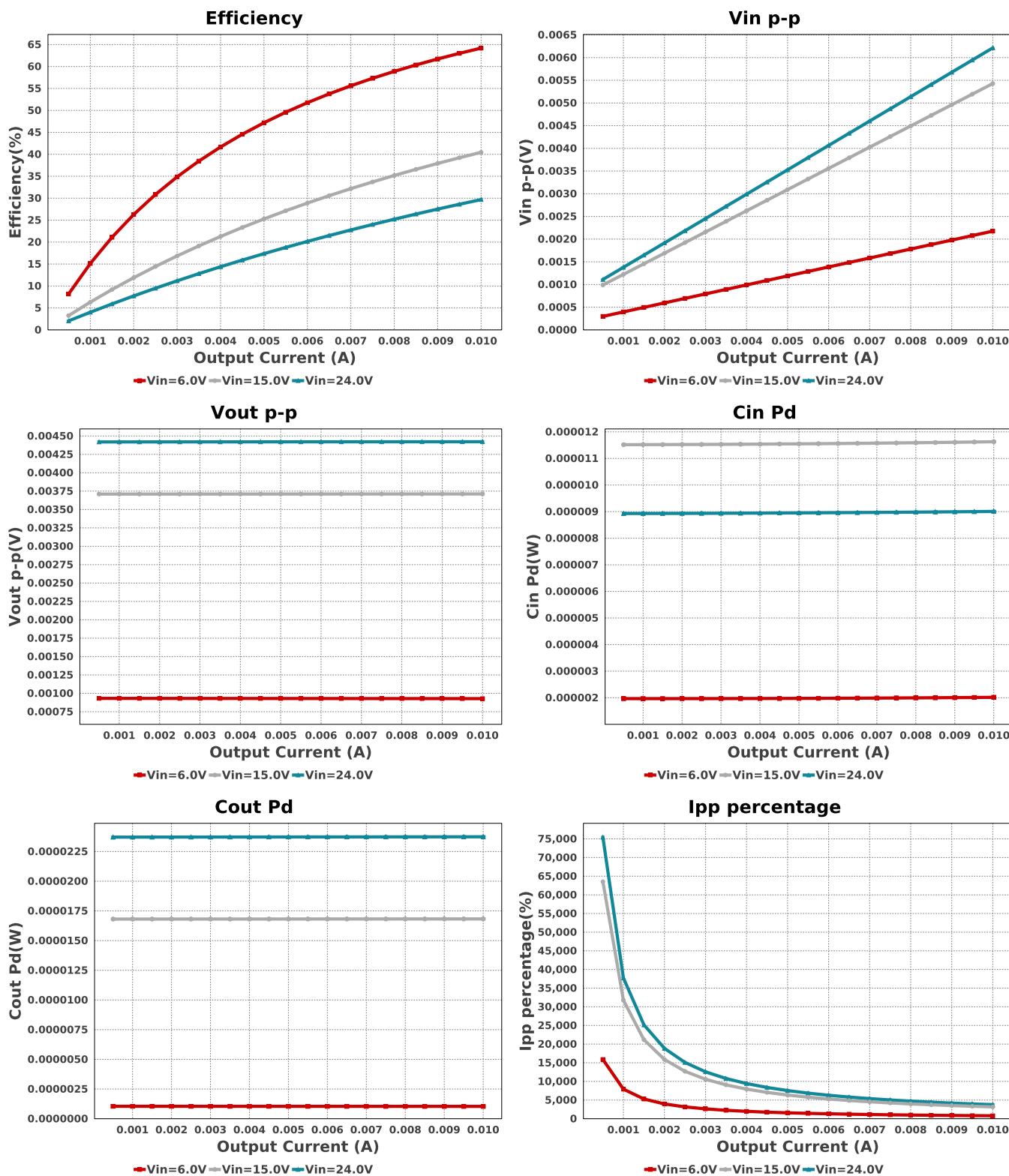
Device = LMR50410XFDBVR  
Topology = Buck  
Created = 2023-03-02 22:45:58.011  
BOM Cost = \$0.75  
BOM Count = 9  
Total Pd = 0.12W

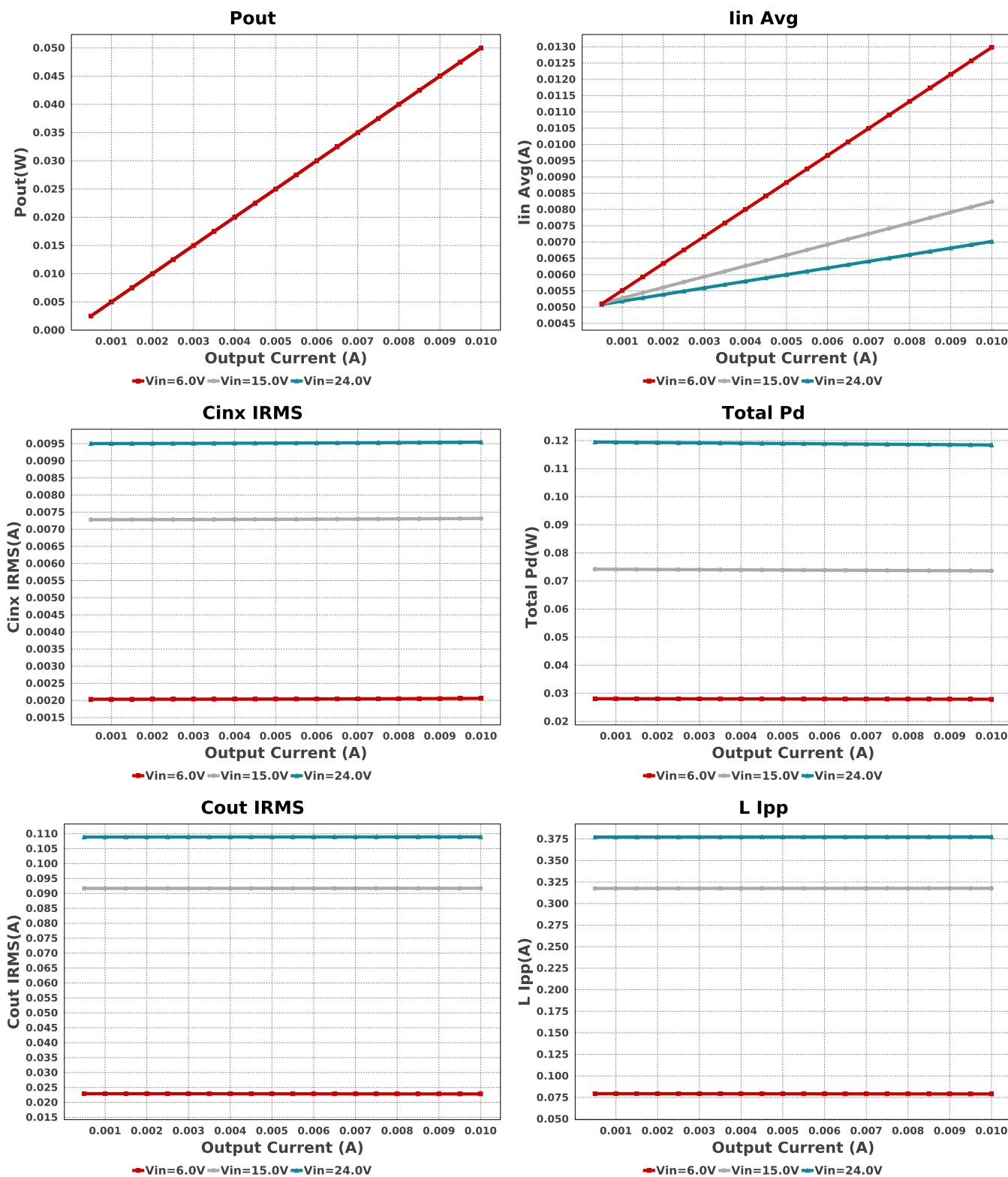


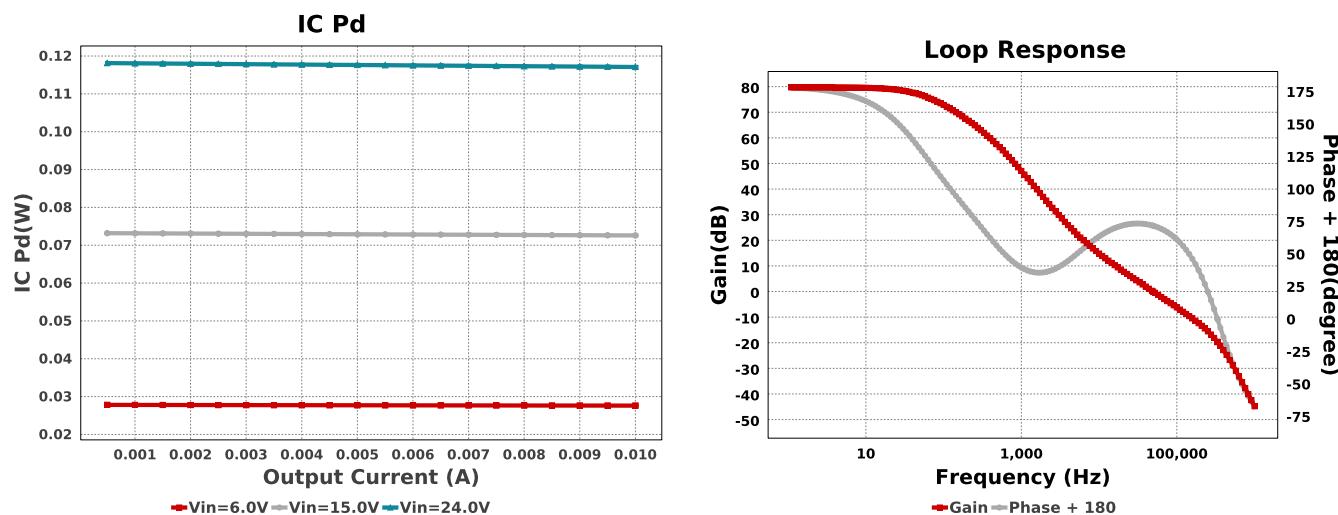
## Electrical BOM

| Name  | Manufacturer      | Part Number                          | Properties  | Qty | Price  | Footprint  |
|-------|-------------------|--------------------------------------|---|-----|--------|--|
| Cboot | MuRata            | GRM155R71C104KA88D<br>Series= X7R    | Cap= 100.0 nF<br>ESR= 1.0 mOhm<br>VDC= 16.0 V<br>IRMS= 0.0 A    | 1   | \$0.01 | ■<br>0402_3 mm <sup>2</sup>  |
| Cin   | TDK               | C1608X7R1V105K080AC<br>Series= X7R   | Cap= 1.0 uF<br>ESR= 5.522 mOhm<br>VDC= 35.0 V<br>IRMS= 2.2162 A | 1   | \$0.05 | ■<br>0603_5 mm <sup>2</sup>  |
| Cinx  | MuRata            | GRM188R71H104KA93D<br>Series= X7R    | Cap= 100.0 nF<br>ESR= 20.0 mOhm<br>VDC= 50.0 V<br>IRMS= 3.8 A   | 1   | \$0.02 | ■<br>0603_5 mm <sup>2</sup>  |
| Cout  | MuRata            | GRM31CR71E106KA12L<br>Series= X7R    | Cap= 10.0 uF<br>ESR= 4.0 mOhm<br>VDC= 25.0 V<br>IRMS= 6.0 A     | 2   | \$0.06 | ■■<br>1206_180_11 mm <sup>2</sup>  |
| L1    | NIC Components    | NPI75C150MTRF                        | L= 15.0 μH<br>90.0 mOhm   | 1   | \$0.11 | <br>IND_NPI75C 94 mm <sup>2</sup> |
| Rffb  | Vishay-Dale       | CRCW040222K1FKED<br>Series= CRCW..e3 | Res= 22.1 kOhm<br>Power= 63.0 mW<br>Tolerance= 1.0%             | 1   | \$0.01 | ■<br>0402_3 mm <sup>2</sup>  |
| Rfbt  | Vishay-Dale       | CRCW040288K7FKED<br>Series= CRCW..e3 | Res= 88.7 kOhm<br>Power= 63.0 mW<br>Tolerance= 1.0%             | 1   | \$0.01 | ■<br>0402_3 mm <sup>2</sup>  |
| U1    | Texas Instruments | LMR50410XFDBVR                       | Switcher  | 1   | \$0.42 | <br>DBV0006A 15 mm <sup>2</sup>   |









## Operating Values

| #   | Name                | Value                 | Category    | Description   |
|-----|---------------------|-----------------------|-------------|---|
| 1.  | Cin IRMS            | 40.388 mA             | Capacitor   | Input capacitor RMS ripple current  |
| 2.  | Cin Pd              | 9.008 $\mu$ W         | Capacitor   | Input capacitor power dissipation   |
| 3.  | Cinx IRMS           | 9.546 mA              | Capacitor   | Bulk capacitor RMS ripple current   |
| 4.  | Cinx Pd             | 1.822 $\mu$ W         | Capacitor   | Bulk capacitor power dissipation  |
| 5.  | Cout IRMS           | 108.956 mA            | Capacitor   | Output capacitor RMS ripple current   |
| 6.  | Cout Pd             | 23.743 $\mu$ W        | Capacitor   | Output capacitor power dissipation  |
| 7.  | IC Ipk              | 198.718 mA            | IC          | Peak switch current in IC   |
| 8.  | IC Pd               | 117.1 mW              | IC          | IC power dissipation  |
| 9.  | IC Tj               | 39.368 degC           | IC          | IC junction temperature   |
| 10. | IC Tolerance        | 15.0 mV               | IC          | IC Feedback Tolerance   |
| 11. | ICThetaJA Effective | 80.0 degC/W           | IC          | Effective IC Junction-to-Ambient Thermal Resistance                           |
| 12. | Iin Avg             | 7.018 mA              | IC          | Average input current   |
| 13. | Ipp percentage      | 3.774 k%              | Inductor    | Inductor ripple current percentage (with respect to average inductor current) |
| 14. | L Ipp               | 377.44 mA             | Inductor    | Peak-to-peak inductor ripple current  |
| 15. | L Pd                | 1.077 mW              | Inductor    | Inductor power dissipation  |
| 16. | Cin Pd              | 9.008 $\mu$ W         | Power       | Input capacitor power dissipation   |
| 17. | Cinx Pd             | 1.822 $\mu$ W         | Power       | Bulk capacitor power dissipation  |
| 18. | Cout Pd             | 23.743 $\mu$ W        | Power       | Output capacitor power dissipation  |
| 19. | IC Pd               | 117.1 mW              | Power       | IC power dissipation  |
| 20. | L Pd                | 1.077 mW              | Power       | Inductor power dissipation  |
| 21. | Total Pd            | 118.441 mW            | Power       | Total Power Dissipation   |
| 22. | BOM Count           | 9                     | System      | Total Design BOM count  |
| 23. | Cross Freq          | 49.598 kHz            | Information | Bode plot crossover frequency   |
| 24. | Duty Cycle          | 20.864 %              | Information | Duty cycle  |
| 25. | Efficiency          | 29.684 %              | Information | Steady state efficiency   |
| 26. | FootPrint           | 149.0 mm <sup>2</sup> | Information | Total Foot Print Area of BOM components                                       |
| 27. | Frequency           | 700.0 kHz             | Information | Switching frequency   |
| 28. | Gain Marg           | -19.807 dB            | Information | Bode Plot Gain Margin   |
| 29. | Iout                | 10.0 mA               | Information | Iout operating point  |
| 30. | Low Freq Gain       | 79.694 dB             | Information | Gain at 1Hz   |
| 31. | Mode                | FCCM                  | Information | Conduction Mode   |
| 32. | Phase Marg          | 72.285 deg            | Information | Bode Plot Phase Margin  |
| 33. | Pout                | 50.0 mW               | Information | Total output power  |
| 34. | Total BOM           | \$0.75                | Information | Total BOM Cost  |
| 35. | Vin                 | 24.0 V                | Information | Vin operating point   |
| 36. | Vin p-p             | 6.214 mV              | Information | Peak-to-peak input voltage  |

| #   | Name           | Value    | Category           | Description  |
|-----|----------------|----------|--------------------|--|
| 37. | Vout           | 5.0 V    | System Information | Operational Output Voltage   |
| 38. | Vout Actual    | 5.014 V  | System Information | Vout Actual calculated based on selected voltage divider resistors                         |
| 39. | Vout Tolerance | 3.142 %  | System Information | Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable |
| 40. | Vout p-p       | 4.422 mV | System Information | Peak-to-peak output ripple voltage   |

## Design Inputs

| Name    | Value      | Description            |
|---------|------------|------------------------|
| Iout    | 10.0 m     | Maximum Output Current |
| VinMax  | 24.0       | Maximum input voltage  |
| VinMin  | 6.0        | Minimum input voltage  |
| Vout    | 5.0        | Output Voltage         |
| base_pn | LMR50410XF | Base Product Number    |
| source  | DC         | Input Source Type      |
| Ta      | 30.0       | Ambient temperature    |

## WEBENCH® Assembly

### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of  $C_{in}$  and  $C_{out}$ , and the inductance and DC resistance of  $L_1$  before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

### Soldering Component to Board

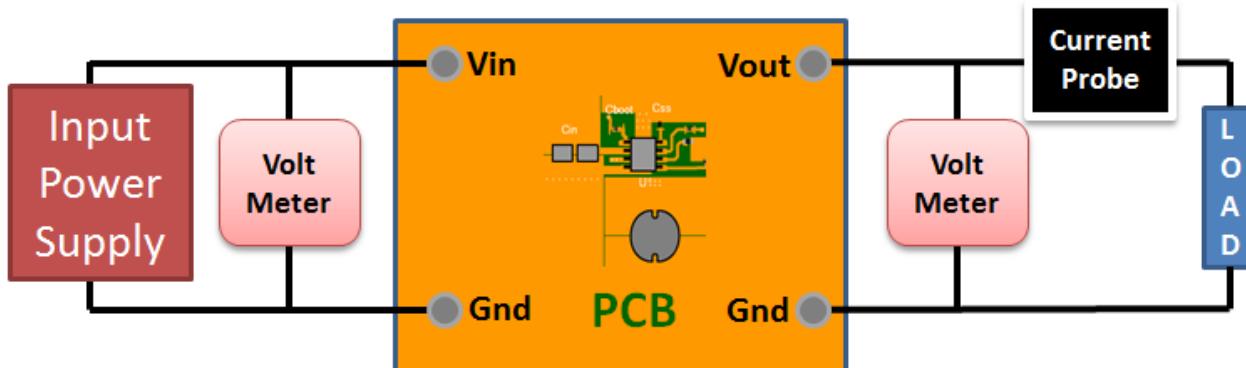
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 6.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to  $V_{in}$  and GND. Connect a digital volt meter and a load if needed to set the minimum  $I_{out}$  of the design from  $V_{out}$  and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between  $V_{in}$  and GND, a load is connected between  $V_{out}$  and GND and a current meter is connected in series between  $V_{out}$  and the load. The load must be able to handle at least rated output power + 50% ( 7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

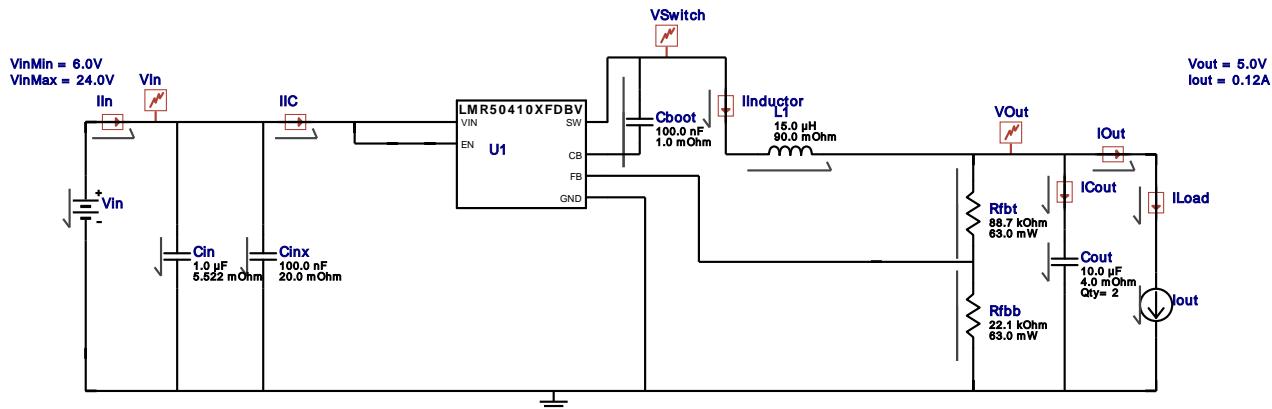


## WEBENCH® Electrical Simulation Report

Design Id = 7839

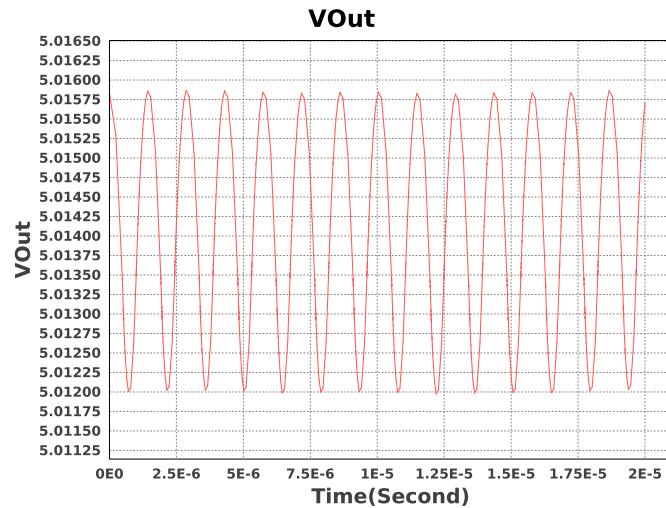
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Simulation Type = Steady State



## Simulation Parameters

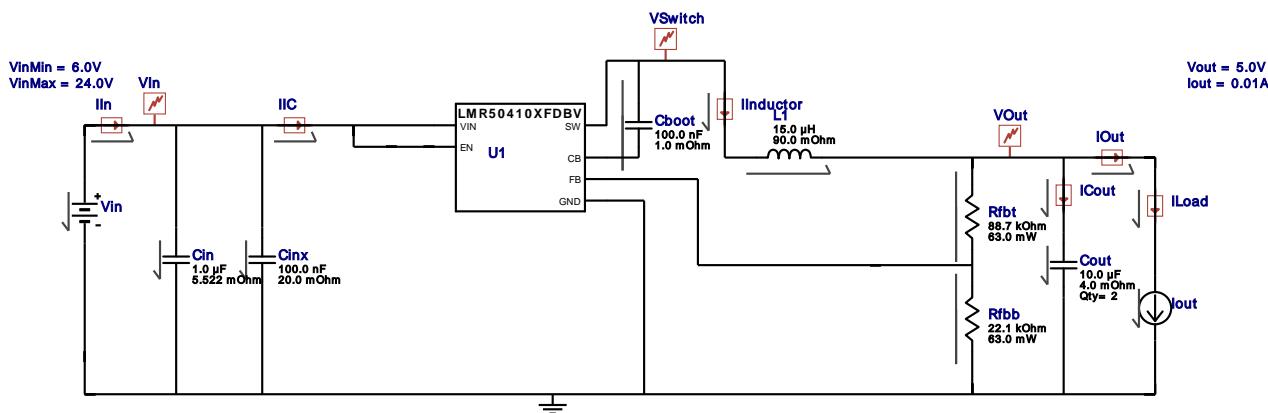
| #  | Name | Parameter Name | Description     | Values |
|----|------|----------------|-----------------|--------|
| 1. | L1   | IC             | Initial Current | 0.12 A |
| 2. | Iout | I              | Output Current  | 0.12 A |



Design Id = 7839

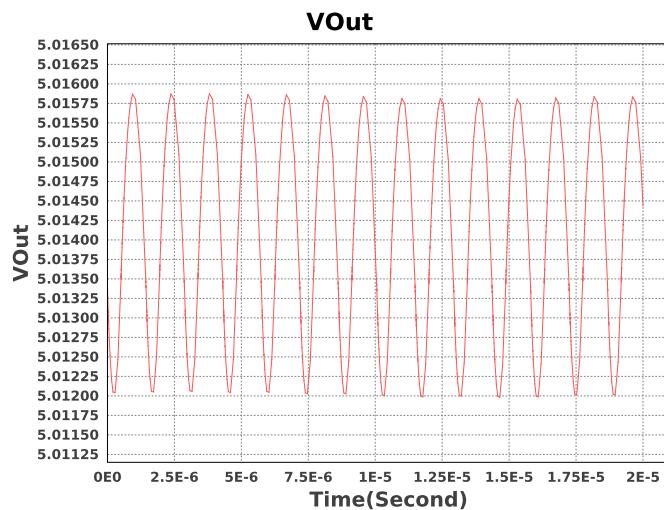
sim\_id = 3

Simulation Type = Steady State



## Simulation Parameters

| #  | Name | Parameter Name | Description     | Values |
|----|------|----------------|-----------------|--------|
| 1. | L1   | IC             | Initial Current | 0.01 A |
| 2. | Iout | I              | Output Current  | 0.01 A |



## Design Assistance

1. Master key : AE3011FD2EE8F4EB[v1]
2. LMR50410XF Product Folder : <http://www.ti.com/product/LMR50410> : contains the data sheet and other resources.

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